

PATENT APPLN. NO. 10/609,022
RESPONSE UNDER 37 C.F.R. §1.111

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REMARKS

The claims have been amended to limit the method of the present invention to a method of adhering a coating of a polymer, metalloid oxide or fluorinated derivatives thereof to a surface of a dielectric layer or passivation layer of a device produced in a CMOS process. I.e., the adhering of a metal coating to a surface of a dielectric layer or passivation layer of a device produced in a CMOS process has been canceled from the scope of the method of the invention.

In the Action of October 8, 2008, the claims of the application are rejected under 35 U.S.C. § 103(a) as being unpatentable over Yeh et al., U.S. Patent Application Publication No. 2002/0197763 A1 ("Yeh"), in view of Kishita, EP 0616012.

Yeh discloses only the forming of a metal layer 72 on a dielectric layer 70. The proposed modification of Yeh will not result in the method of the present invention as recited in the claims of the application, particularly as amended.

Removal of the 35 U.S.C. § 103(a) rejection and an allowance of the claims of the application are in order and are respectfully requested.

The foregoing is a complete and proper response to the Office Action dated October 8, 2008.

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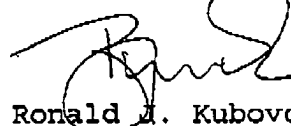
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In the event that this paper is not considered to be timely filed, applicants hereby petition for an appropriate extension of time. The fee for any such extension may be charged to our Deposit Account No. 111833.

In the event any additional fees are required, please also charge our Deposit Account No. 111833.

Respectfully submitted,

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